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2-Step  
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By:

*Morgan N. All*

Date:

*July 2, 2003*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Lothar Bauch et al.

Applic. No. : 10/082,554

Filed : February 25, 2002

Title : Stacked VIA with Specially Designed Landing Pad for Integrated Semiconductor Structures

Examiner : Pershelle L. Greene

Group Art Unit : 2826

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A M E N D M E N T

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

S i r :

Responsive to the non-final Office action dated May 21, 2003,  
kindly amend the above-identified application as follows: